

July 2015

FGA4060ADF 600 V, 40 A Field Stop Trench IGBT

Features

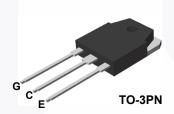
- Maximum Junction Temperature : T_J = 175°C
- · Positive Temperaure Co-efficient for Easy Parallel Operating
- · High Current Capability
- Low Saturation Voltage: $V_{CE(sat)} = 1.8 \text{ V(Typ.)} @ I_C = 40 \text{ A}$
- 100% of the Parts Tested for I_{LM}(1)
- · High Input Impedance
- · Fast Switching
- · Tighten Parameter Distribution
- · RoHS Compliant

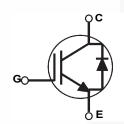
General Description

This ADF IGBT series adopted Field Stop Trench 3rd generation IGBT which offer extreme low Vce(sat) and much faster switching characteristics for outstanding efficiency. And this kind of technology is fully optimized to variety PFC (Power Factor Correction) topology; Single boost, Multi channel interleaved etc with over 20KHz switching performance. TO3P package provide Super Low thermal resistance for much wider SOA for system stability.

Applications

PFC topology for Home appliance: Single Boost, Multi channel Interleaved etc.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description		FGA4060ADF	Unit		
V _{CES}	Collector to Emitter Voltage		600	V		
M	Gate to Emitter Voltage		± 20	V		
V_{GES}	Transient Gate to Emitter Voltage		± 30	V		
I _C	Collector Current	@ T _C = 25°C	80	Α		
iC.	Collector Current	@ T _C = 100°C	40	Α		
I _{LM (1)}	Pulsed Collector Current	@ T _C = 25°C	120	Α		
I _{CM (2)}	Pulsed Collector Current		120	Α		
	Diode Forward Current	@ T _C = 25°C	3	Α		
I _{F (3)}	Diode Forward Current	@ T _C = 100°C	1.5	Α		
I _{FM (2)}	Pulsed Diode Maximum Forward Currer	6	А			
P _D	Maximum Power Dissipation	@ T _C = 25°C	238	W		
' D	Maximum Power Dissipation @ $T_C = 100^{\circ}C$		119	W		
T _J	Operating Junction Temperature		-55 to +175	°C		
T _{stg}	Storage Temperature Range		-55 to +175	°C		
T _L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C		

Notes:

- 1. V_{CC} = 400 V, V_{GE} = 15 V, I_{C} =120 A, R_{G} = 120 Ω , Inductive Load.
- Repetitive rating: Pulse width limited by max. junction temperature.
- 3. The purpose of diode is protection for negative voltage.

Thermal Characteristics

Symbol	Parameter	FGA4060ADF	Unit		
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case, Max.	0.63	°C/W		
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case, Max.	5	°C/W		
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	°C/W		

Package Marking and Ordering Information

Part Number Top Mark		Package	Packing Method	Reel Size	Tape Width	Qty per Tube	
FGA4060ADF	FGA4060ADF	TO-3PN	Tube	-	-	30	

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V$, $I_C = 1$ mA	600	-	-	V
ΔBV _{CES} / ΔΤ _J	Temperature Coefficient of Breakdown Voltage	I _C = 1 mA, Reference to 25°C	-	0.6	-	V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}$, $V_{GE} = 0$ V	-	-	250	μА
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	±400	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	I_C = 40 mA, V_{CE} = V_{GE}	4.1	5.6	7.6	V
		I _C = 40 A, V _{GE} = 15 V	-	1.8	2.3	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 40 A, V _{GE} = 15 V, T _C = 175°C	-	2.31	-	V
Dynamic C	haracteristics					
C _{ies}	Input Capacitance		-	1525	-	pF
C _{oes}	Output Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz	-	60	-	pF
C _{res}	Reverse Transfer Capacitance	1 = 1WIDZ	-	20	-	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time		T -/	16.8	-	ns
t _r	Rise Time		-	34.4	-	ns
t _{d(off)}	Turn-Off Delay Time	V _{CC} = 400 V, I _C = 40 A,	-	54.4	-	ns
t _f	Fall Time	$R_G = 6 \Omega$, $V_{GE} = 15 V$,	-	10	-	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C	-	1.37	/	mJ
E _{off}	Turn-Off Switching Loss		-	0.25	- //	mJ
E _{ts}	Total Switching Loss		-	1.62	-	mJ
t _{d(on)}	Turn-On Delay Time		-	16	- \	ns
t _r	Rise Time		_	35.2	-	ns
t _{d(off)}	Turn-Off Delay Time	V_{CC} = 400 V, I_{C} = 40 A, R_{G} = 6 Ω , V_{GE} = 15 V, Inductive Load, T_{C} = 175°C	-	57.6	-	ns
t _f	Fall Time		-	12.8	-	ns
E _{on}	Turn-On Switching Loss		-	1.89	-	mJ
	Turn Off Cuitobing Loop		_	0.47	_	mJ
E _{off}	Turn-Off Switching Loss			0		1110

Electrical Characteristics of the IGBT (Continued)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Unit
Qg	Total Gate Charge		-	55.5	-	nC
Q _{ge}	Gate to Emitter Charge	$V_{CE} = 400 \text{ V}, I_{C} = 40 \text{ A},$ $V_{GE} = 15 \text{ V}$	-	9.8	-	nC
Q _{gc}	Gate to Collector Charge		-	21	-	nC

Electrical Characteristics of the Diode T_C = 25°C unless otherwise noted

Symbol	Parameter		Test Conditions		Min.	Тур.	Max	Unit	
V _{FM}	Diode Forward Voltage	I _F = 3	3 A		T _C = 25°C	-	1.6	2.3	V
FIVI					T _C = 175°C	-	1.4	-	
E _{rec}	Reverse Recovery Energy				T _C = 175°C	-	29.7	-	uJ
t	Diode Reverse Recovery Time	$I_F = 3 \text{ A}, dI_F/dt = 200 \text{ A}/\mu\text{s}$	-	T _C = 25°C	/ -	26	-	ns	
rr L				T _C = 175°C	-	153	-	110	
Q _{rr}	Diode Reverse Recovery Charge			-	T _C = 25°C	-	35	-	nC
~11	2.500 No. 50. 50 No. 50				T _C = 175°C	-	305	-]

Figure 1. Typical Output Characteristics

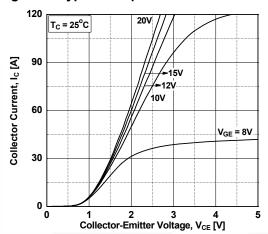


Figure 3. Typical Saturation Voltage Characteristics

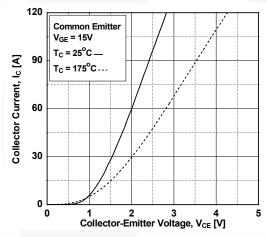


Figure 5. Saturation Voltage vs. V_{GE}

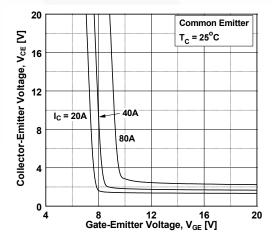


Figure 2. Typical Output Characteristics

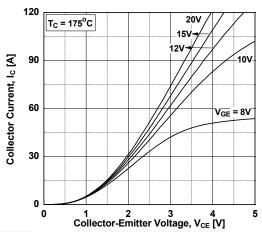


Figure 4. Saturation Voltage vs. Case
Temperature at Variant Current Level

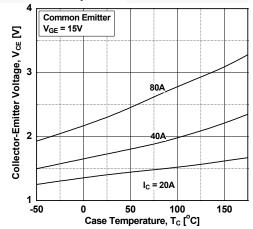


Figure 6. Saturation Voltage vs. V_{GE}

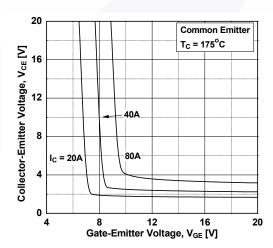


Figure 7. Capacitance Characteristics

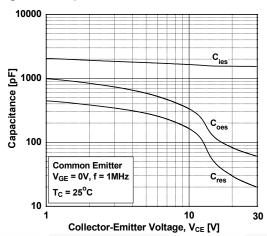


Figure 9. Turn-on Characteristics vs.
Gate Resistance

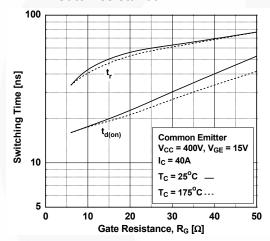


Figure 11. Switching Loss vs.
Gate Resistance

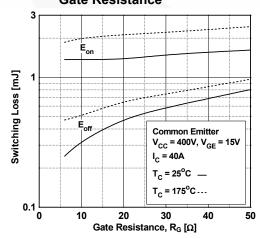


Figure 8. Gate charge Characteristics

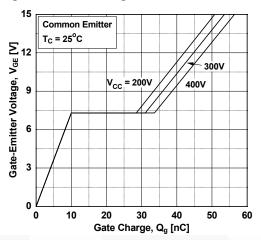


Figure 10. Turn-off Characteristics vs.
Gate Resistance

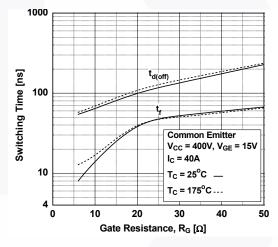


Figure 12. Turn-on Characteristics vs. Collector Current

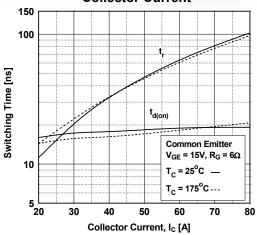
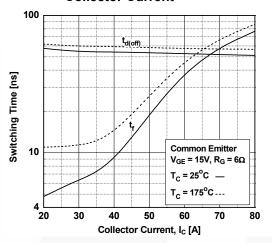


Figure 13. Turn-off Characteristics vs. **Collector Current**



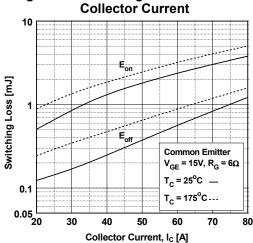


Figure 14. Switching Loss vs.

Figure 15. Load Current Vs. Frequency

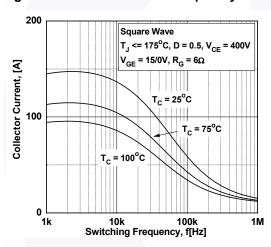


Figure 16. SOA Characteristics

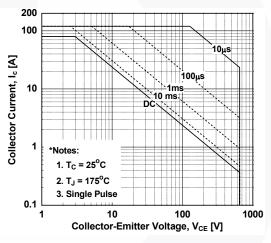


Figure 17. Forward Characteristics

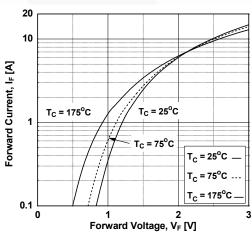


Figure 18. Reverse Recovery Current

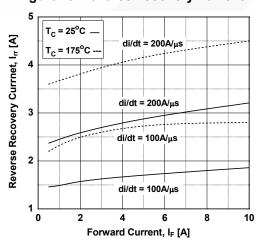


Figure 19. Reverse Recovery Time

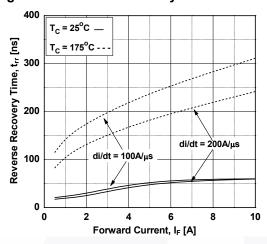


Figure 20. Stored Charge

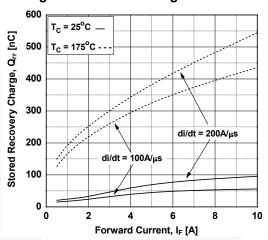


Figure 21. Transient Thermal Impedance of IGBT

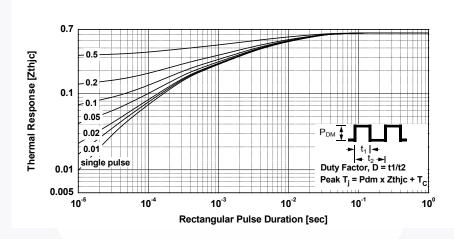
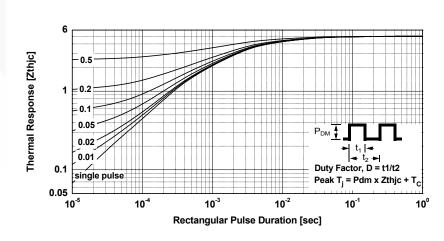
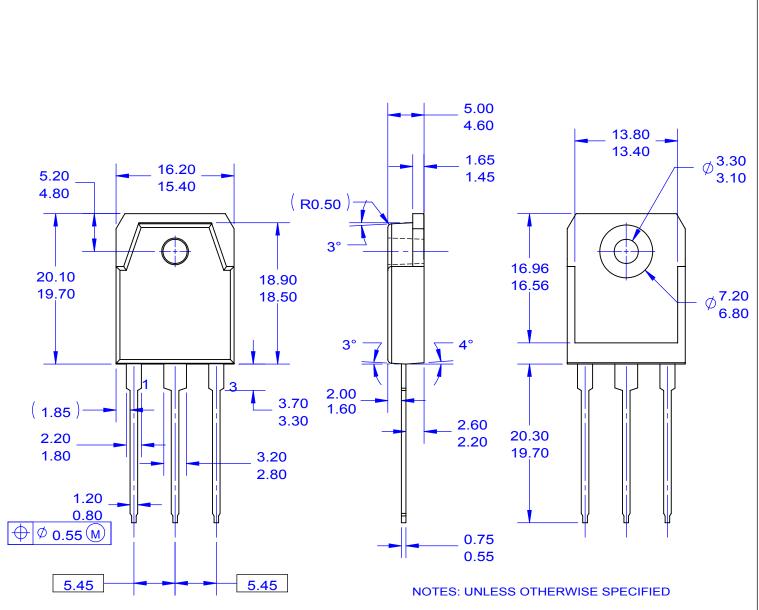
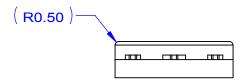


Figure 22. Transient Thermal Impedance of Diode







- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
- E) DRAWING FILE NAME: TO3PN03AREV2.
- F) FAIRCHILD SEMICONDUCTOR.



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